

## Miniature Glass Passivated Single-Phase Surface Mount Bridge Rectifiers

Reverse Voltage 50V to 1000V Forward Current 1.0 Ampere

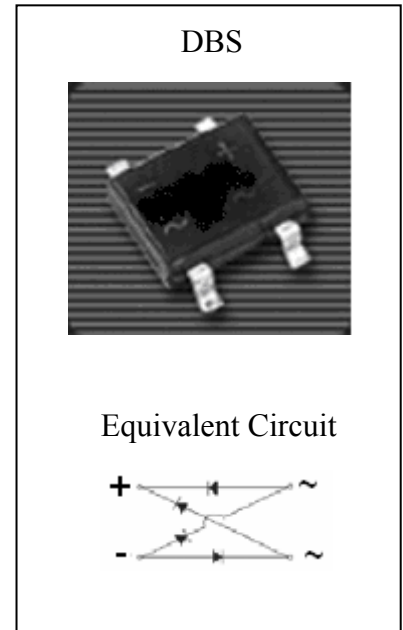
# DB101SG thru DB107SG

### Features

- Ideal for printed circuit boards
- Applicable for automotive insertion
- High surge current capability
- High temperature soldering guaranteed: 260 °C, 10 seconds, 0.375”(9.5mm) lead length at 5 lbs( 2.3kg) tension.
- Pb-free lead plating and halogen-free package

### Mechanical Data

- Case: Molded plastic body, epoxy meets UL 94V-0 flammability rating
- Terminals: Pure tin plated, solderable per J-STD-002B and JESD22-B102D
- Polarity : as marked on body



### Maximum Ratings and Electrical Characteristics

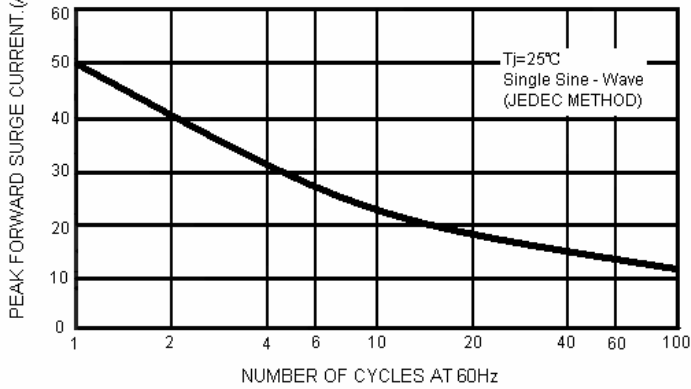
(Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.)

Parameter	Symbol	Type							Units
		DB101SG	DB102SG	DB103SG	DB104SG	DB105SG	DB106SG	DB107SG	
Repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	V
Maximum instantaneous forward voltage drop per leg, I <sub>F</sub> =1A	V <sub>F</sub>	1.1							V
Maximum average forward output rectified current at T <sub>A</sub> =40 °C	I <sub>F(AV)</sub>	1 (Note 1)							A
Peak forward surge current @8.3ms single half sine wave superimposed on rated load (JEDEC method)	I <sub>FSM</sub>	50							A
Rating for fusing (t<8.3ms)	I <sup>2</sup> t	10							A <sup>2</sup> s
Maximum DC reverse current at rated DC blocking voltage per leg	T <sub>A</sub> =25 °C	10							μA
	T <sub>A</sub> =125 °C	500							
Typical thermal resistance per leg (Note 1)	R <sub>θJA</sub>	40							°C /W
	R <sub>θJL</sub>	15							
Typical diode junction capacitance per leg @f=1MHz and applied 4V reverse voltage	C <sub>J</sub>	25							pF
Storage temperature range	T <sub>stg</sub>	-55 ~ +150							°C
Operating temperature range	T <sub>J</sub>	-55 ~ +150							°C

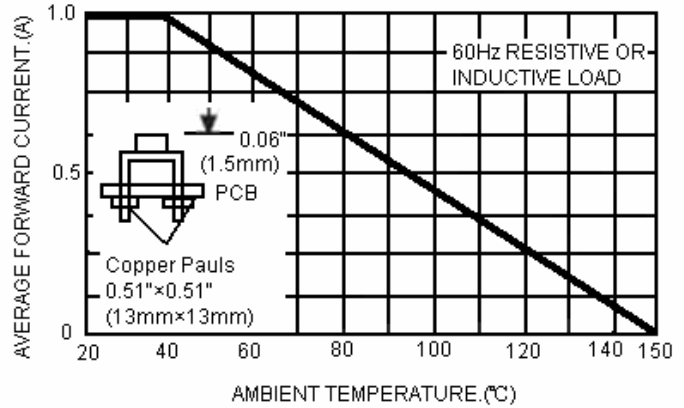
Note : 1.Units mounted on PCB with 0.47”x0.47”(12 mmx12mm) copper pads.

## RATING AND CHARACTERISTIC CURVES DB101SG THRU DB107SG

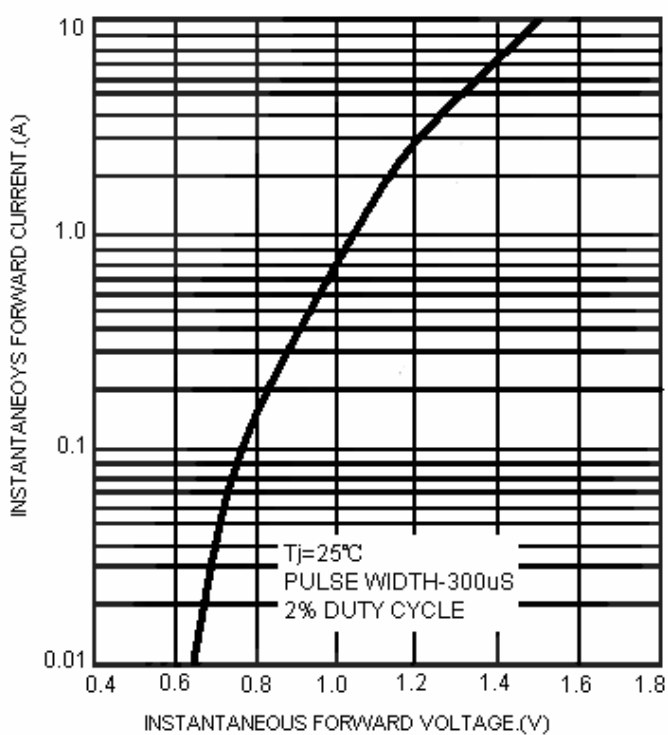
**FIG.1-MAXIMUM NONO-REPETITIVE FORWARD SURGE CURRENT PER BRIDGE ELEMENT**



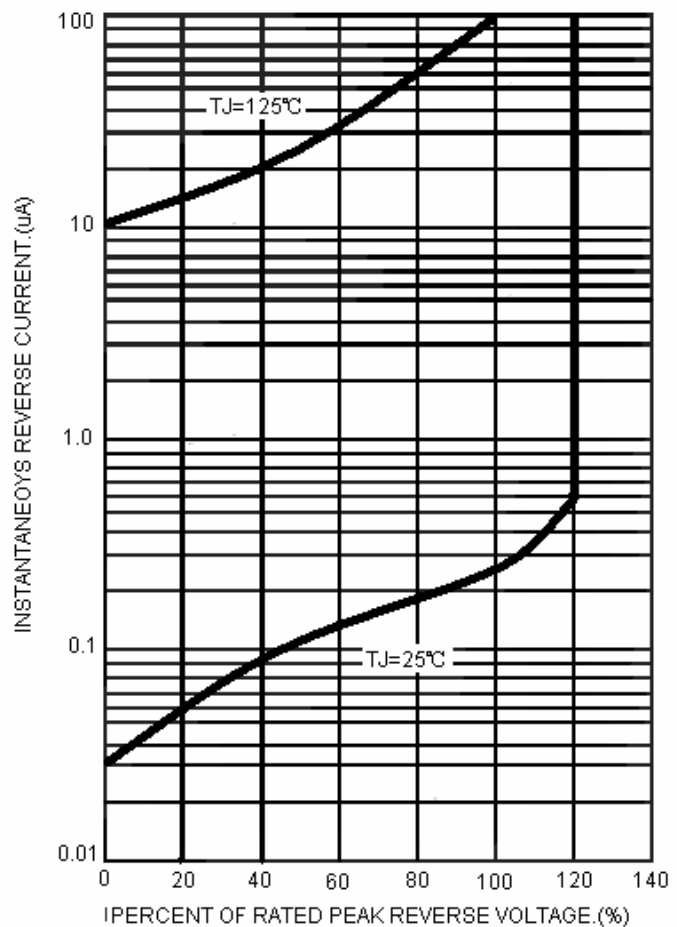
**FIG.2-MAXIMUM FORWARD CURRENT DERATING CURVE**



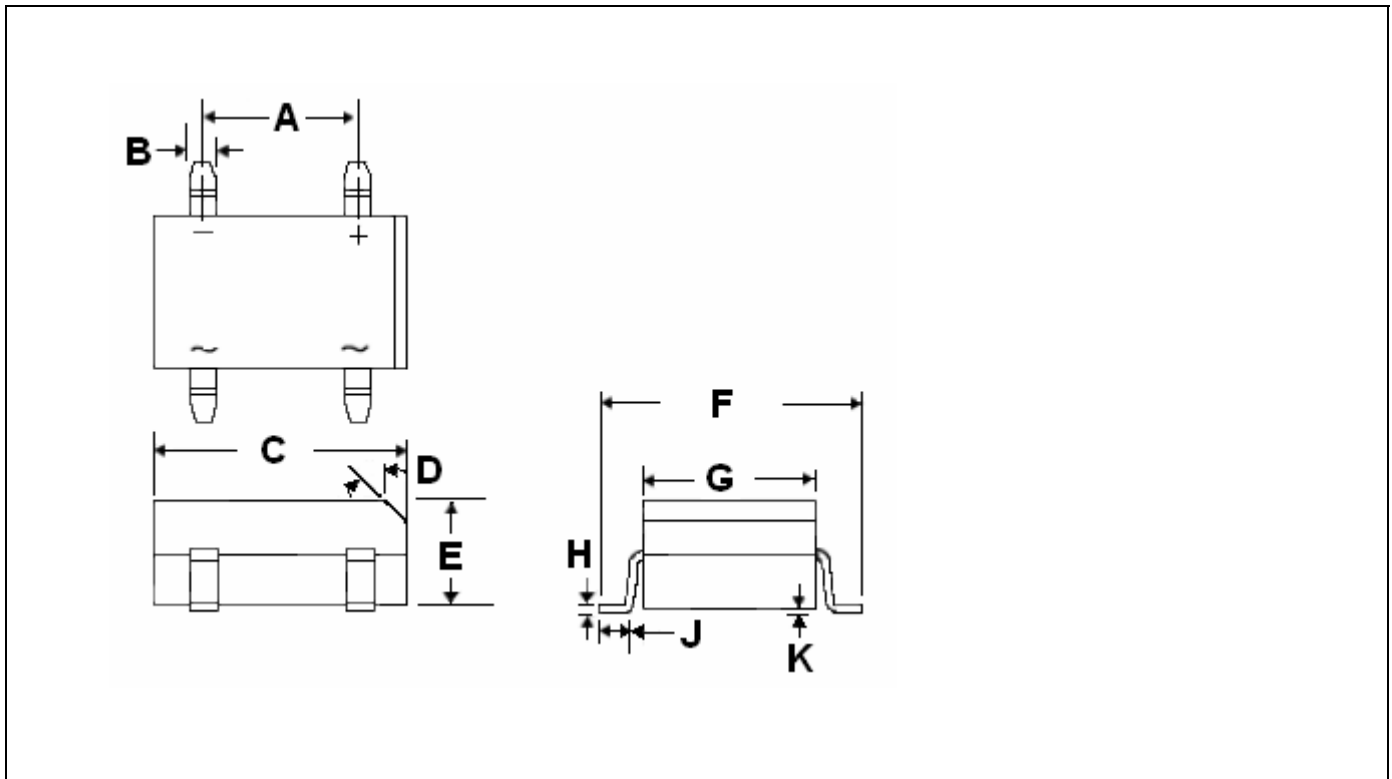
**FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS PER BRIDGE ELEMENT**



**FIG.4-TYPICAL REVERSE CHARACTERISTICS PER BRIDGE ELEMENT**



**DBS Dimension**



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.195	0.205	5.000	5.200	F	0.386	0.404	9.800	10.300
B	0.040	0.047	1.020	1.200	G	0.245	0.255	6.200	6.500
C	0.320	0.335	8.130	8.510	H	0.009	0.013	0.220	0.330
D	45° (typ)		45° (typ)		J	0.040	0.060	1.020	1.530
E	0.120	0.130	3.050	3.300	K	0.003	0.013	0.076	0.330

Notes : 1.Controlling dimension : millimeters.  
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

**Material :**

- Lead :Pure tin plated.
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0.

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